

FOR IMMEDIATE RELEASE

HDP User Group Announces RBP Chemical Technology as its Newest Member

Cave Creek, Arizona July 12, 2016. The High Density Packaging (HDP) User Group headquartered in the United States is pleased to announce that RBP Chemical Technology has become a member.

"We are pleased to join HDPUG and contribute to the advancement of electronics packaging technology. RBP brings over 35 years of technique and know-how in a wide range of technologies used in the manufacturing of high reliability printed circuit boards, IC substrates and silicon based substrates. RBP's expertise is in high density circuit formation, low profile adhesion promoters and surface treatment and passivation of metal surfaces " said Michael Carano, V.P. Technology and Business Development for RBP Chemical Technology.

"RBP Chemical Technology is an excellent addition to the HDP User Group Membership. The Staff and Members of our organization are looking forward to working with them on our projects and activities.", said Marshall Andrews, Executive Director of HDP User Group.

As a Member, RBP Chemical Technology will join over 50 of the major companies involved in collaborative research addressing the major technical and environmental issues facing the electronics industry today. Their participation will complement the other member companies and help keep HDP User Group technical projects moving forward.

About RBP Chemical Technology

RBP Chemical Technology was founded in 1954. RBP develops, manufactures and specialty chemicals and processes used in the fabrication of printed circuit boards, semiconductors and IC substrates. Company expertise resides in surface preparation, metallization, circuit formation, HDI, solderability enhancement and processes for TSV and RDL. Further emphasis on processes to enhance signal integrity and long-term reliability.

For more information, visit <u>www.RBPchemical.com</u> or contact Michael Carano at mcarano@rbpchemcial.net, +1 414.258.0911.



About HDP User Group

HDP User Group (www.hdpug.org) is a global research and development organization based in Cave Creek Arizona, is dedicated to "reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly". This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas, Singapore, and Dollar, U.K.

For more information, visit HDP User Group on the Internet at <u>www.hdpug.org</u> or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963